| ASSOCIATION CONNECTING<br>ASSOCIATION CONNECTING<br>ELECTRONICS INDUSTRIES®<br>international and Pa | PC. Bannockl   | burn, Illinois, A     | Il rights reserved untions. | under both    | This docume<br>level parts, t   | ent is a declaration entities the declaration entities and the declaration entities and the declaration entities and the declaration entities are an | on of the su<br>compasses                  | bstances v<br>all lower | vithin the manufactu<br>level materials for v | rer listed i<br>which the r     | tem. Note:<br>nanufacture | if the item is an as<br>r has engineering | sembly with low responsibility. |  |
|---|--|-----------------------|-----------------------------|---------------|---|--|--|-------------------------|---|---------------------------------|---------------------------|---|---------------------------------|--|
|   | 21.1 IPC Web Site for Information on IPC-1752 Standard Form<br>http://www.ipc.org/IPC-175x Distr |                       |                             |               | * Declaration Class *<br>Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Infor |  |  |                         |   | lfg Informa                     | tion                      |   |                                 |  |
| Supplier Information  |  |                       |                             |               |   |  |  |                         |   |                                 |                           |   |                                 |  |
| Company name* Company   |  |                       | any unique ID               |               |   | Unique ID Authority  |  |                         |   | Respon                          | Response Date*            |   |                                 |  |
| nsemi   |  |                       |                             |               |   |  |  |                         |   | 2024-05                         | 2024-05-06                |   |                                 |  |
| Contact Name  | tet Name Title - Contact   |                       |                             |               | Phone - Contact*  |  |  |                         | Email - Contact*                              |                                 |                           |   |                                 |  |
| roduct-Env-Stewards Product Envi  |  |                       | viro Compliance             |               |   | NA   |  |                         |   | Product-Env-Stewards@onsemi.com |                           |   |                                 |  |
| Authorized Representative* Title - Representative   |  |                       | esentative                  |               |   | Phone - Representative*  |  |                         |   | Email - Representative*         |                           |   |                                 |  |
| Product-Env-Stewards Product F  |  |                       | luct Enviro Compliance      |               |   | NA   |  |                         |   | Product-Env-Stewards@onsemi.com |                           |   |                                 |  |
| Requester Item Number   | Mfr Iten   | n Number              | Mfr Item Name               |               |   | Effective Date   | ve Date Version Manufactur                 |                         | lanufacturing Site                            | Weight*                         |                           | UOM                                       | Unit Type                       |  |
|   | FDPC80   | FDPC8014S PT9N 30/12  |                             | & PT9N 25/12  |   | 2024-05-06   |  | PI                      | РВВ   |                                 | 121.566                   | mg  | Each                            |  |
| Aanufacturing Proccess Informa  | tion   |                       | ·                           |               |   |  |  |                         |   |                                 |                           |   |                                 |  |
| Terminal Plating / Grid Array M   | aterial 7  | l Terminal Base Alloy |                             | J-STD-020 MSI | L Rating  | Peak Proce   | k Process Body Temperature Max Time at Pea |                         | k Tempera                                     | ture Num                        | ber of Reflow Cyc         | les                                       |                                 |  |
| Matte Tin (Sn) - annealed CU Alloy  |  |                       | 1                           |               | 260   |  | С  | 30                      | secor   | nds 3                           |                           |   |                                 |  |
| omments   |  |                       |                             |               |   |  |  |                         |   |                                 |                           |   |                                 |  |
| vel 1 - maximum time at peak temperat   | ure during so  | Idering is 10-3       | 0 seconds                   |               |   |  |  |                         |   |                                 |                           |   |                                 |  |
| or more information regarding material  | composition  | please refer to       | page 3                      |               |   |  |  |                         |   |                                 |                           |   |                                 |  |

| RoHS Material Composition Declaration  |  |   |   | Declaration Type *  | Detailed  |  |  |  |  |  |  |
|--|--|---|---|---|---|--|--|--|--|--|--|
| Directive 2015/863/EU amending RoHS<br>Directive 2011/65/EU  | (Pb), Mercury (Hg), Hexavalent Chro  | RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP). |   |   |   |  |  |  |  |  |  |
| cadmium, hexavalentchromium, polybromina<br>contains a RoHS restricted substance inexces<br>encompass all such components. Supplier cer<br>as of the date that Supplier completes this for<br>Company acknowledges that Supplier may h<br>independently verified information provided<br>certification in this paragraph. If the Company | ated biphenyls and/or polybrominated dip<br>s of an applicable quantity limit, please in<br>iffies that it gathered the information it pr<br>m.Supplier acknowledges that Company<br>ave relied on informationprovided by oth<br>by others, Supplier agrees that, at a minir<br>and the Supplier enter into a written agr<br>esource of the Supplier's liability and the | henyl ethers (each a "RoHS restricted substa<br>ndicate below which, if any, RoHS exemption<br>ovides in this form using appropriate methoo<br>will rely on this certification in determining<br>ers in completing this form, and that Supplie<br>num, itssuppliers have provided certification<br>eement with respect to the identified part, the<br>Company's remedies for issues that arise reg                                | nce") in exco<br>n you believe<br>ls to ensure i<br>the compliar<br>r may not ha<br>s regarding t<br>terms and co | e may apply. If the part is an assembly with low<br>s accuracy and that such information is true an<br>ce of its products with European Union member<br>de independently verified such information. Ho<br>neir contributions to the part, and those certifica | ove. If a homogeneous material within the part<br>er level components, the declaration shall<br>d correct to the best of its knowledge and belief,<br>er state laws that implement the RoHS Directive.<br>wever, in situations where Supplier has not<br>ations are at least as comprehensive as the<br>anty rights and/or remedies provided as part of |  |  |  |  |  |  |
| RoHS Declaration * 4 - Item(   | s) does not contain RoHS restricted subst  | ances per the definition above except for sele  | ected exempt  | ions Supplier Acceptance  | * Accepted  |  |  |  |  |  |  |
| Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).  |  |   |   |   |   |  |  |  |  |  |  |
| Exemption List Version   | EL-2011/534/EU   |   |   |   |   |  |  |  |  |  |  |
| Declaration Signature  |  |   |   |   |   |  |  |  |  |  |  |
| Instructions: Complete all of the required<br>Requester) and click on Submit Form to h   |  |   | e drop-dowi   | a. This will display the signature area. Digita   | lly sign the declaration (if required by the  |  |  |  |  |  |  |
| Supplier Digital Signature   | astislav Drska   | Le  |   |   |   |  |  |  |  |  |  |

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

| Homogeneous Material | Weight | Unit of Measure | Level    | Substance                  | CAS        | Exempt | Weight | Unit of Measure |
|----------------------|--------|-----------------|----------|----------------------------|------------|--------|--------|-----------------|
| Clip                 | 19.1   | mg              | Supplier | Zinc (Zn)                  | 7440-66-6  |        | 0.025  | mg              |
|                      |        |                 | Supplier | Iron (Fe)                  | 7439-89-6  |        | 0.458  | mg              |
|                      |        |                 | Supplier | Copper (Cu)                | 7440-50-8  |        | 18.617 | mg              |
| Die                  | 1.6    | mg              | Supplier | Silicon (Si)               | 7440-21-3  |        | 1.6    | mg              |
| Die Attach Solder    | 1.936  | mg              | Supplier | Silver (Ag)                | 7440-22-4  |        | 0.0484 | mg              |
|                      |        |                 | А        | Lead (Pb)                  | 7439-92-1  | 7a     | 1.7908 | mg              |
|                      |        |                 | Supplier | Tin (Sn)                   | 7440-31-5  |        | 0.0968 | mg              |
| Lead Frame           | 46.396 | mg              | Supplier | Silver (Ag)                | 7440-22-4  |        | 0.636  | mg              |
|                      |        |                 | Supplier | Zinc (Zn)                  | 7440-66-6  |        | 0.06   | mg              |
|                      |        |                 | Supplier | Iron (Fe)                  | 7439-89-6  |        | 1.1    | mg              |
|                      |        |                 | Supplier | Copper (Cu)                | 7440-50-8  |        | 44.6   | mg              |
| Mold Compound-Black  | 43.59  | mg              | Supplier | Ortho Cresol Novolac Resin | 29690-82-2 |        | 2.18   | mg              |
|                      |        |                 | Supplier | Fused Silica (SiO2)        | 60676-86-0 |        | 40.1   | mg              |
|                      |        |                 | Supplier | Phenolic Resin (Novolac)   | 9003-35-4  |        | 1.31   | mg              |
| Plating              | 8.33   | mg              | Supplier | Tin (Sn)                   | 7440-31-5  |        | 8.33   | mg              |
| Wire Bond            | 0.614  | mg              | Supplier | Gold (Au)                  | 7440-57-5  |        | 0.581  | mg              |
|                      |        |                 | Supplier | Copper (Cu)                | 7440-50-8  |        | 0.033  | mg              |